

Appl. No. 10/708,705
Amdt. dated July 6, 2005
Reply to Office action of May 17, 2005

REMARKS/ARGUMENTS

1. Rejection of claims 1-9 under 35 U.S.C. 112, second paragraph:

- 5 Claims 1-9 are rejected under 35 U.S.C. 112, second paragraph for failing to particularly point out and distinctly claim the subject matter which applicants regards as the invention. Claim 1 requires that the solder pad separate the first bonding line from other bonding lines. The scope of the claim is nebulous, since it is not known how a solder pad can be used to isolate lines from one another.

10 **Response:**

Claim 1 has been amended to remove this indefinite language. No other changes to claim 1 have been made. Reconsideration of the amended claim 1 is respectfully requested.

15 2. Rejection of claims 1, 4, and 9 under 35 U.S.C. 103(a):

Claims 1, 4, and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsunoda et al. (US 6,417,532) in view of Schroeder et al. (US 4,513,355).

Response:

- 20 As the examiner has stated in the above-indicated Office action, Tsunoda et al. do not teach a package including a solder pad soldered to the first bonding line at a point on the first bonding line between the bonding pad of the die and the trace of the circuit board.

- 25 In addition, the applicant submits that Schroeder et al. also do not teach this feature. In col.2, lines 22-25, Schroeder et al. state, "The words 'wire bond(s)' refer to the welded or soldered connection between a bonding wire or connection means, and a bonding pad or bonding area." Therefore, Schroeder et al. only teach that the wire bond is connected to

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the bonding pad on a chip or a bonding area on a package through a soldered connection, so as to provide a means for connecting the chip and the package through the wire bond.

5 However, Schroeder et al. do not teach a "solder pad soldered to the first bonding line at a point on the first bonding line between the bonding pad of the die and the trace of the circuit board", as is recited in claim 1. That is, Schroeder et al. do not teach an intermediate solder pad on the bonding line between the connections to the die and the circuit board. Therefore, reconsideration of claim 1 is respectfully requested. Claims 4 and 9 are dependent on claim 1, and should be allowed if claim 1 is allowed.

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3. Rejection of claims 1, 2, 8, and 9 under 35 U.S.C. 103(a):

Claims 1, 2, 8, and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gilliland (US 2004/0118587) in view of Schroeder et al.

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Response:

As the examiner has stated in the above-indicated Office action, Tsunoda et al. do not teach a package including a solder pad soldered to the first bonding line at a point on the first bonding line between the bonding pad of the die and the trace of the circuit board.

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In addition, Schroeder et al. also do not teach this feature for the same reasons explained above. Claims 2, 8, and 9 are dependent on claim 1, and should be allowed if claim 1 is allowed. Reconsideration of claims 1, 2, 8, and 9 is requested.

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4. Rejection of claims 3 and 5-7 under 35 U.S.C. 103(a):

Claims 3 and 5-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gilliland in view of Schroeder et al. and further in view of Chiang (US 6,744,126).

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Response:

Claims 3 and 5-7 are dependent on claim 1, and should be allowed if claim 1 is allowed. Reconsideration of claims 3 and 5-7 is requested.

5 5. Rejection of claims 10 and 13 under 35 U.S.C. 103(a):

Claims 10 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsunoda et al. in view of Kinayman et al. (US 2003/0151133).

Response:

10 Claims 10 and 13 are cancelled, and are no longer in need of consideration.

6. Rejection of claims 10, 11, and 17 under 35 U.S.C. 103(a):

Claims 10, 11, and 17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gilliland in view of Kinayman et al.

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Response:

Claims 10, 11, and 17 are cancelled, and are no longer in need of consideration.

7. Rejection of claims 12 and 14-16 under 35 U.S.C. 103(a):

20 Claims 12 and 14-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Gilliland in view of Kinayman et al and further in view of Chiang.

Response:

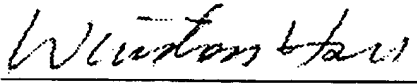
Claims 12 and 14-16 are cancelled, and are no longer in need of consideration.

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In view of the above arguments in favor of patentability, the applicant respectfully requests that the final rejection of claims 1-9 be withdrawn.

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Respectfully submitted,



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- 10 Note: Please leave a message in my voice mail if you need to talk to me. The time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.